NRG™ SLE 66R35E7

Wafer specification

About this document

This document is valid only in combination with the latest version of the general issue of the chip delivery specification for wafer.

Document number: Z8F50723335

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1 Chip dimensions

Location	Lot no	Type		
Dresden	ZA...	A	Stepping size:	0.902 mm x 0.818 mm
			Scribe line:	82 µm
Scribe line without sealring:			According to Chip layout	

2 Possible systems on the wafer

Location	Lot no	Type	Possible systems
Dresden	ZA...	A	40.126

3 Pad metalization on front

Location	Lot no	Type		
Dresden	ZA...	A	Material:	AlCu
			Thickness:	650 nm ± 100 nm

4 Passivation

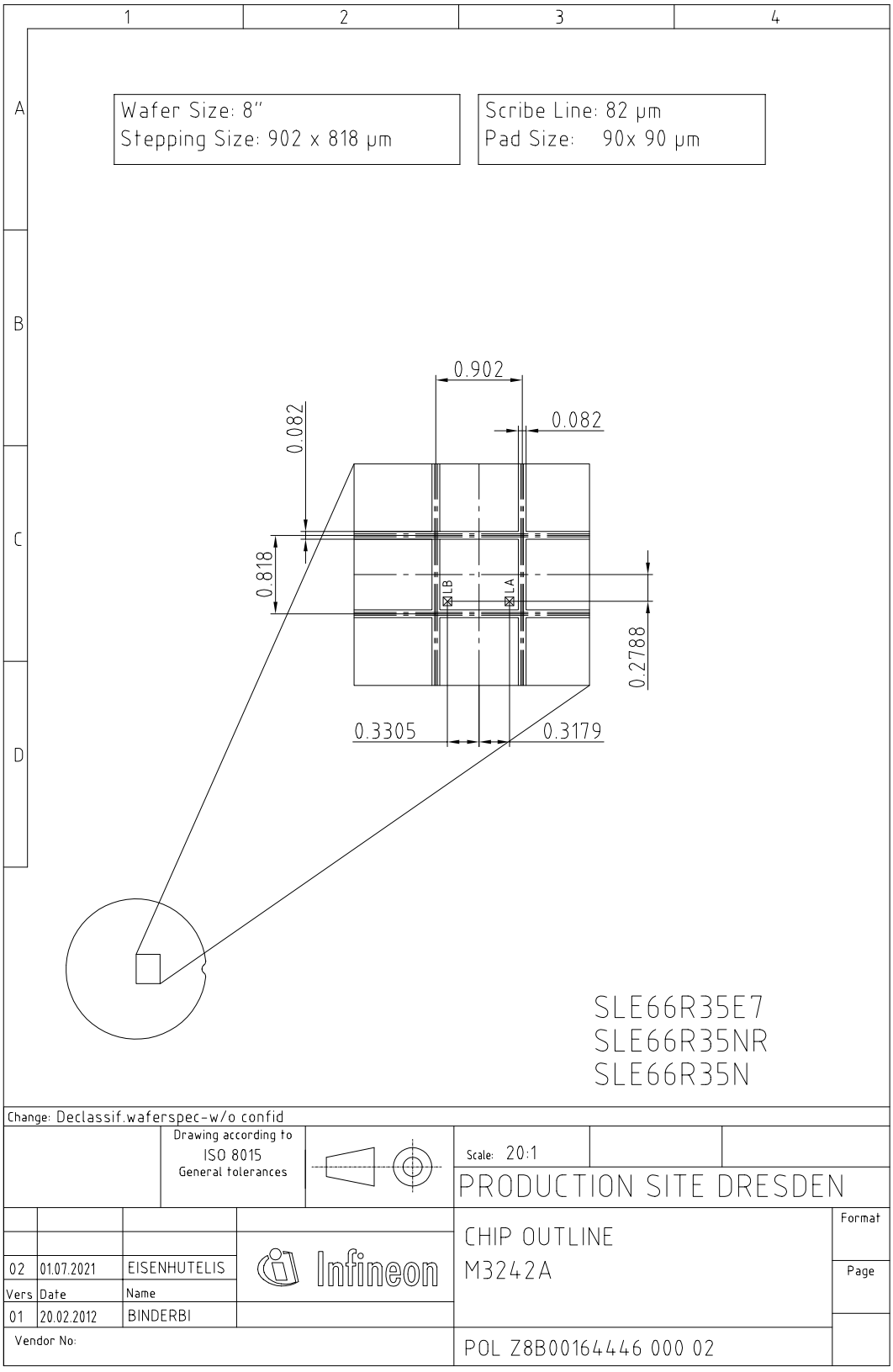
Location	Lot no	Type		
Dresden	ZA...	A	Material:	Thickness:
			Oxinitride	650 nm ± 100 nm
			Photoimide	2.5 µm ± 0.5 µm

5 Bonding area (pad)

Pad size:	See Chip layout
Bond pad material:	Depends on respective technology (see Pad metalization on front)

Recommended condition for die and wire bonding climate: 23°C ± 1K, 30% - 60% relative humidity

A Chip layout, Type A



Revision history

Date	Revision	Change position	Change description
2023-03-17	Revision 3.0	All	Updated editorial changes
2015-04-10	Revision 2.0	All	Updated sales code
2012-02-20	Revision 1.0	All	Initial release

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